L Number	Hits	Search Text	DB	Time stamp
1	1	("6353267").PN.	USPAT	2002/06/30 00:11
2	1		USPAT	2002/06/30 00:11
3	2	1 ,	USPAT	2002/06/30 00:22
4	30128		USPAT;	2002/06/30 01:13
		(bump or ball)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
5	28848	/dorrigo and /neat as all as	IBM_TDB	
	20040	(device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)	USPAT;	2002/06/30 02:19
		(bump of ball)) and (ead<20010427)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
6	4679	((device and (post or column or pillar)	USPAT;	2002/06/30 01:15
		and (bump or ball)) and (@ad<20010427))	US-PGPUB;	2002/08/30 01:13
		and pad	EPO; JPO;	
			DERWENT;	1
			IBM TDB	
7	566		USPAT;	2002/06/30 01:30
		and (bump or ball)) and (@ad<20010427))	US-PGPUB;	
		and (pad with (post or column or pillar))	EPO; JPO;	
			DERWENT;	
8	1	(#6101400#) 793	IBM_TDB	
9	1 1	("6191493").PN. 6191493.URPN.	USPAT	2002/06/30 01:59
10	19		USPAT	2002/06/30 01:46
	1.7	"5139969" "5171716" "5205036"	USPAT	2002/06/30 01:47
		"5237013" "5244838" "5304460"		
		"5304512" "5321303" "5331235"		
		"5371044" "5373190" "5427938"		
		"5438478" "5474958" "6007357"		
		"6014318").PN.		
11	1154	257/786.ccls.	USPAT;	2002/06/30 02:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
12	1087	257/7061- 1 /0 1:000104071	IBM_TDB	
12	1087	257/786.ccls. and (@ad<20010427)	USPAT;	2002/06/30 02:09
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
13	1045	257/786.ccls. and (@ad<20000427)	USPAT;	2002/06/30 02:01
		, ,	US-PGPUB;	2002/00/30 02:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	48	(and and and and and and and and	USPAT;	2002/06/30 02:10
		ball and (pillar or column or post)	US-PGPUB;	ĺ
			EPO; JPO;	
			DERWENT;	
15	372	257/620.ccls. and (@ad<20010427)	IBM_TDB USPAT;	2002/06/30 02:09
	5,2	231, 020.0013. and (ead\20010421)	USPAT; US-PGPUB;	2002/06/30 02:09
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	7	(257/620.ccls. and (@ad<20010427)) and	USPAT;	2002/06/30 02:52
		ball and (pillar or column or post)	US-PGPUB;	· · · · · · · · · · · · · · · · · · ·
			EPO; JPO;	
			DERWENT;	
1.7	آ ۽	120/460	IBM_TDB	
17	8	438/462.ccls. and ball and (pillar or	USPAT;	2002/06/30 02:16
	ļ	column or post)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
·				

10				
18	11	438/460.ccls. and ball and (pillar or column or post)	USPAT; US-PGPUB;	2002/06/30 02:16
			EPO; JPO;	
10	0.1	100 (100	DERWENT; IBM TDB	
19	21	438/113.ccls. and ball and (pillar or column or post)	USPAT;	2002/06/30 02:18
		ostalar of post,	US-PGPUB; EPO; JPO;	
			DERWENT;	
20	852	((center or middle) with (pad or trace or	IBM_TDB USPAT;	2002/06/30 02:19
	ĺ	electrode)) and ball and (pillar or	US-PGPUB;	2002/06/30 02:19
		column or post)	EPO; JPO; DERWENT;	
21	7.07		IBM TDB	
21	797	(((center or middle) with (pad or trace or electrode)) and ball and (pillar or	USPAT;	2002/06/30 02:53
		column or post)) and (@ad<20010427)	US-PGPUB; EPO; JPO;	
			DERWENT;	
22	628	((((center or middle) with (pad or trace	IBM_TDB USPAT;	2002/06/30 02:53
		or electrode)) and ball and (pillar or column or post)) and (@ad<20010427)) and	US-PGPUB;	2002/00/30 02:55
	İ	(device or chip or wafer)	EPO; JPO; DERWENT;	
23	1	("6191493").PN.	IBM_TDB	
24	32051	(step or stepped) with (molding or mold or	USPAT;	2002/06/30 02:51 2002/06/30 02:52
		encapsulant or rein)	US-PGPUB;	2002/00/30 02:32
			EPO; JPO; DERWENT;	
25	811	1/2422	IBM_TDB	
	011	((step or stepped) with (molding or mold or encapsulant or rein)) and ball and	USPAT; US-PGPUB;	2002/06/30 02:53
		(pillar or column or post)	EPO; JPO;	
			DERWENT; IBM TDB	
26	766	(((step or stepped) with (molding or mold	USPAT;	2002/06/30 02:53
		or encapsulant or rein)) and ball and (pillar or column or post)) and	US-PGPUB; EPO; JPO;	
		(@ad<20010427)	DERWENT;	
27	494	((((step or stepped) with (molding or mold	IBM_TDB USPAT;	2002/06/30 03:05
		or encapsulant or rein)) and ball and (pillar or column or post)) and	US-PGPUB;	2002/00/30 03.03
		(@ad<20010427)) and (device or chip or	EPO; JPO; DERWENT;	
28	2306	wafer)	IBM TDB	
	2300	(dielectric or insulating or insulation) near polyimide	USPAT; US-PGPUB;	2002/06/30 03:06
			EPO; JPO;	
			DERWENT; IBM TDB	
29	382	((dielectric or insulating or insulation)	USPĀT;	2002/06/30 03:07
		near polyimide) and 257/\$.ccls.	US-PGPUB; EPO; JPO;	
			DERWENT;	
	L		IBM_TDB	

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L Number	Hits	Search Text	DB	Time stamp
1	899	257/787.ccls	USPAT	2002/06/30 13:43
2	810	257/787.ccls. and (@ad<20000423)	USPAT	2002/06/30 14:22
3	0	(stepped adj shape) near encapsulant	USPAT	2002/06/30 14:10
4	0	(stepped adj shape) with encapsulant	USPAT	2002/06/30 14:09
5	2	(stepped adj shape) near (encapsulant or	USPAT;	2002/06/30 14:13
		mold)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	0	(stepped adj shape) with encapsulant	USPAT;	2002/06/30 14:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	1	("6351030").PN.	USPAT	2002/06/30 14:21
8	45	(remove or cut) near encapsulant	USPAT;	2002/06/30 14:25
]			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
9	36	((remove or cut) near encapsulant) and	USPAT	2002/06/30 14:26
		(@ad<20000428)		
10	273	(remove or cut) with (encapsulant or	USPAT;	2002/06/30 14:25
		(moldong adj resin))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	192	((remove or cut) with (encapsulant or	USPAT	2002/06/30 14:26
		(moldong adj resin))) and (@ad<20000428)		